

### OVLAW4CB7

#### Features:

- High luminous intensity
- Through-hole type
- Clear lens
- High efficiency



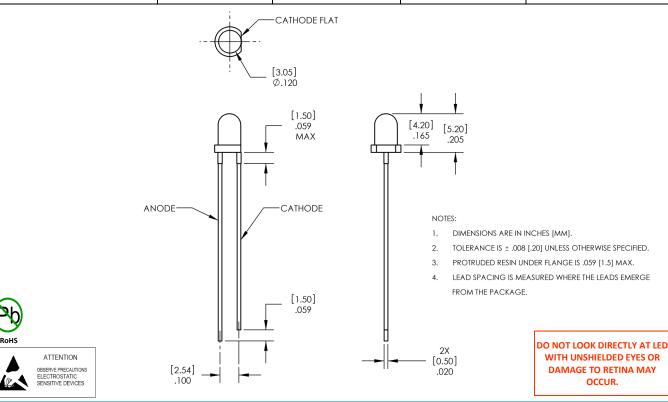
#### **Description:**

The OVLAW4CB7 is a round 3mm white high-intensity through-hole lamp with a 40° viewing angle. It is designed for wide-angle uniform light output.

#### **Applications:**

- Indicators for medical, industrial, consumer and office equipment
- Indicators for white goods and home appliances
- Interior and exterior architectural and accent lighting
- Signs and digital information displays, video screen non-color and RGB presentation
- Automotive backlighting and indicators

| Part Number | Material | Emitted Color | Intensity Typ. mcd | Lens Color |
|-------------|----------|---------------|--------------------|------------|
| OVLAW4CB7   | InGaN    | White         | 6200               | Clear      |



#### General Note



OVLAW4CB7

## **Electrical Specifications**

#### **Absolute Maximum Ratings** (T<sub>A</sub> = 25° C unless otherwise noted)

| Storage Temperature Range                                    | -40 ~ +100° C |
|--|---------------|
| Operating Temperature Range                                  | -40 ~ +100° C |
| Reverse Voltage  | 5 V           |
| Power Dissipation  | 100 mW        |
| Average Forward Current                                      | 25 mA         |
| Peak Forward Current (Duty Ratio = 1/10, Pulse Width =0.1ms) | 100 mA        |
| Current Linearity vs Ambient Temperature                     | -0.29 mA/° C  |
| LED Junction Temperature                                     | 125° C        |
| Electrostatic Discharge Classification (JEDEC-JESD22-A114F)  | Class 1C      |
| Lead Soldering Temperature (5 seconds maximum)               | 260° C        |
| Lead Soldering Temperature (5 seconds maximum)               | 260° C        |

### **Electrical Characteristics** (T<sub>A</sub> = 25° C unless otherwise noted)

| SYMBOL         | PARAMETER                | MIN   | TYP   | MAX | UNITS | TEST CONDITIONS        |
|----------------|--------------------------|-------|-------|-----|-------|------------------------|
| I <sub>V</sub> | Luminous Intensity       | 4,360 | 6,200 |     | mcd   | I <sub>F</sub> = 20 mA |
| 20½            | 50% Power Angle          |       | 40    |     | deg   | I <sub>F</sub> = 20 mA |
| V <sub>F</sub> | Forward Voltage          |       | 3.2   | 4.0 | V     | I <sub>F</sub> = 20 mA |
| I <sub>R</sub> | Reverse Current          |       |       | 10  | μΑ    | V <sub>R</sub> = 5 V   |
| х              | Chromaticity Coordinates |       | 0.31  |     |       | I <sub>F</sub> = 20 mA |
| у              | Chromaticity Coordinates |       | 0.32  |     |       | I <sub>F</sub> = 20 mA |

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## OVLAW4CB7

#### **Typical Electro-Optical Characteristics Curves**

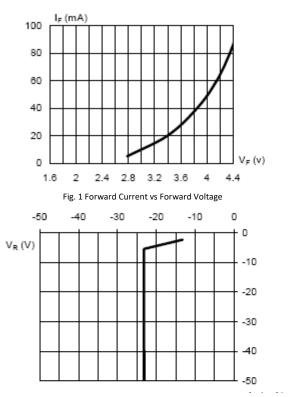


Fig. 3 Reverse Current vs. Reverse Voltage I<sub>R (μA)</sub>

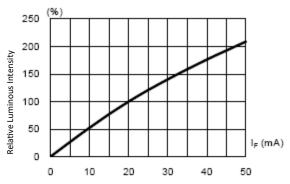
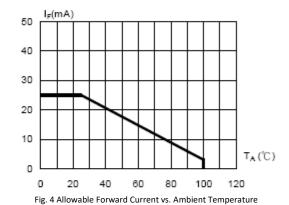


Fig. 2 Luminous Intensity vs. Forward Current



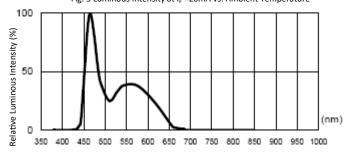
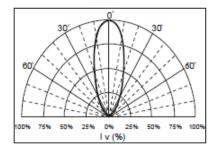


Fig. 6 Relative Luminous Intensity vs. Wavelength



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#### **Beam Pattern**



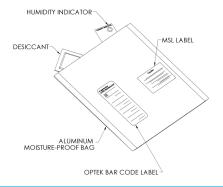
#### Soldering:

Soldering heat may damage the LED. Careful attention should be paid during the soldering process and PCB assembly. In order to eliminate the stress of heat shock, please solder the LEDs no closer than 3mm from the base of the epoxy bulb.

#### **Recommended Soldering Conditions:**

|                               | Wave Soldering | Manual Solder Dipping | Hand Soldering by Iron |
|-------------------------------|----------------|-----------------------|------------------------|
| re-heat Temperature 105°C Max |                |                       |                        |
| Pre-heat Time                 | 30 seconds Max |                       |                        |
| Peak Temperature              | 250°C Max      | 260°C Max             | 350°C Max              |
| Dwell Time                    | 3 seconds Max  | 5 seconds Max         | 3 seconds Max          |

#### Packaging: 500 pcs per bulk bag





## OVLAW4CB7

#### **Reliability Test**

LED lamps are checked by reliability tests based on MIL standards.

### 1. Test Conditions, Acceptable Criteria & Results:

| Classi-<br>fication | Test Item                           | Standard<br>Test Method       | Test Conditions                                       | Duration      | Unit | Acc / Rej<br>Criteria | Result |
|---------------------|-------------------------------------|-------------------------------|---|---------------|------|-----------------------|--------|
| Life<br>Test        | Operation Life Test<br>(OLT)        | MIL-STD-750D<br>Method 1026.3 | T <sub>A</sub> =25°C , I <sub>F</sub> =30mA *         | 1000 Hrs      | 100  | 0 / 1                 | Pass   |
|                     |                                     | MIL-STD-750D<br>Method 1032.1 | T <sub>A</sub> =100°C                                 | 1000 Hrs      | 100  | 0 / 1                 | Pass   |
| Test                | Low Temperature<br>Storage (LTS)    | MIL-STD-750D<br>Method 1032.1 | T <sub>A</sub> =−40°C                                 | 1000 Hrs      | 100  | 0 / 1                 | Pass   |
| Environment Test    | Temp. & Humidity<br>with Bias (THB) | MIL-STD-750D<br>Method 103B   | T <sub>A</sub> =85°C , Rh=85% I <sub>F</sub> =20mA ** | 500 Hrs       | 100  | 0 / 1                 | Pass   |
| Envii               | Thermal Shock<br>Test (TST)         | MIL-STD-750D<br>Method 1056.1 | 0°C ~ 100°C<br>2min 2min                              | 100<br>cycles | 100  | 0 / 1                 | Pass   |
|                     | Temperature<br>Cycling Test (TCT)   | MIL-STD-750D<br>Method 1051.5 | -40°C ~ 25°C~ 100°C ~ 25°C<br>30min 5min 30min 5min   | 100<br>cycles | 100  | 0 / 1                 | Pass   |
| Test                | Solderability                       | MIL-STD-750D<br>Method 2026.4 | 235±5°C → 5 sec                                       | 1 time        | 20   | 0 / 1                 | Pass   |
| Mechanical Test     | Resistance to<br>Soldering Heat     | MIL-STD-750D<br>Method 2031.1 | 260±5°C → 5 sec                                       | 1 time        | 20   | 0 / 1                 | Pass   |
| Мес                 | Lead Integrity                      | MIL-STD-750D<br>Method 2036.3 | Load 2.5N (0.25kgf)<br>0"~90"~0" · bend               | 3 times       | 20   | 0 / 1                 | Pass   |

Remark : (\*)  $I_F = 30$ mA for AlInGaP chip :  $I_F = 20$ mA for InGaN chip (\*\*)  $I_F = 20$ mA for AlInGaP chip :  $I_F = 10$ mA for InGaN chip

### 2. Failure Criteria (T<sub>A</sub> =25°C):

| Test Item          | Symbol         | Test Conditions       | Criteria for Judgment |           |  |
|--------------------|----------------|-----------------------|-----------------------|-----------|--|
| Test Helli         |                |                       | Min.                  | Max.      |  |
| Luminous Intensity | $I_V$          | I <sub>F</sub> =20 mA | LSL×0.7 **            |           |  |
| Forward Voltage    | V <sub>F</sub> | I <sub>F</sub> =20 mA |                       | USL×1.1 * |  |

(\*) USL : Upper Standard Level , (\*\*) LSL : Lower Standard Level